

15 Watts • 50 Volts • 128us, 10% 960-1215MHz

### **E Class Driver GaN Transistor – Key Features**

- 960-1215MHz 15W Pulsed Output Power 128us, 10% Pulsing
- Common Source Class AB 50VDD Bias Voltage
- >60% Efficiency
- 18.1 dB Typical Power Gain
- 0.2 dB Typical Excellent Gain Flatness
- Extremely Compact Size General Purpose Driver 3 package options
- IFF, Mode-S, DME, TACAN, TCAS avionics applications
- · All gold metallization and eutectic die attach for highest reliability
- $50\Omega$  in/out lumped element very small footprint plug & play pallets available

### **ABSOLUTE MAXIMUM RATINGS**

### **Maximum Power Dissipation**

Device Dissipation @ 25°C 37 W

### **Maximum Voltage and Current**

Drain-Source Voltage (VDSS) 150 V Gate-Source Voltage (VGS) -8 to +0 V

#### **Maximum Temperatures**

Storage Temperature (TSTG) -55 to +125 °C
Operating Junction Temperature +200 °C

### **CASE OUTLINES**



55-QQ (0.160" x 0.550" - E)



55-QQP (0.160"x0.230" - EL)



55-78029 (0.600" x 1.200" - EP)

## **ELECTRICAL CHARACTERISTICS @ 25°C**

Symbol	Characteristics	Test Conditions	Min	Тур	Max	Units
P <sub>OUT</sub>	Output Power	P <sub>IN</sub> =0.32W, Freq=960,1090,1215 MHz	15	19		W
$G_P$	Power Gain	P <sub>IN</sub> =0.32W, Freq=960,1090,1215 MHz	17.5	18.1		dB
$\eta_{D}$	Drain Efficiency	P <sub>IN</sub> =0.32W, Freq=960,1090,1215 MHz	60	65		%
Dr	Droop	P <sub>IN</sub> =0.32W, Freq=960,1090,1215 MHz		0.1	0.5	dB
VSWR-T	Load Mismatch Tolerance	P <sub>IN</sub> =0.32W, Freq=1090MHz			5:1	

Bias Condition: V<sub>DD</sub>=+50V, Idq=10mA constant current (V<sub>GS</sub>= -2.0 ~ -4.5V typical)

## FUNCTIONAL CHARACTERISTICS @ 25°C

$I_{D(Off)}$	Drain leakage current	$V_{GS} = -8V, V_D = 50V$		1.0	mA
$I_{G(Off)}$	Gate leakage current	$V_{GS} = -8V$ , $V_D = 0V$		0.2	mA

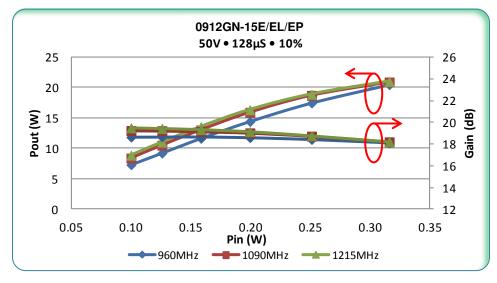
Export Classification: EAR-99

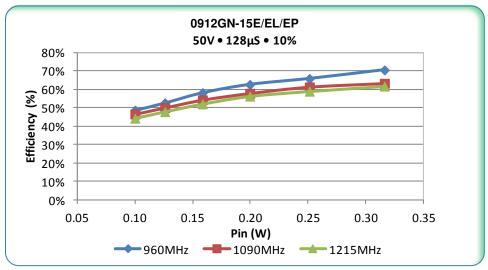


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### TYPICAL BROAD BAND PERFORMACE DATA - 128us, 10% PULSING

Frequency	P <sub>IN</sub> (mW)	P <sub>OUT</sub> (W)	I <sub>D</sub> (mA)	IRL (dB)	η <sub>D</sub> (%)	G <sub>P</sub> (dB)	Droop (dB)
960 MHz	320	20.5	68	-9.3	71	18.1	0.2
1090 MHz	320	20.9	76	-9.2	63	18.2	0.2
1215 MHz	320	18.2	78	-13.5	62	18.2	0.3

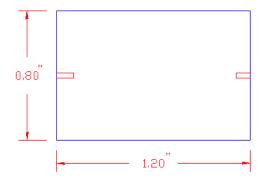






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## **Transistor Test Fixture Overall Dimension**



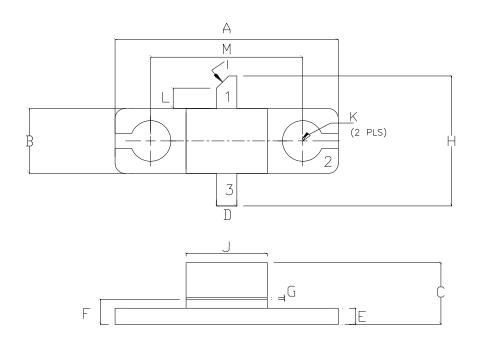
Dimensions in inches.

Test Fixture available upon request



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### **55-QQ PACKAGE DIMENSION**



Dim	Millimeter	Tol	Inches	Tol
Α	13.970	0.250	0.550	0.010
В	4.570	0.250	0.160	0.010
С	3.860	0.330	0.152	0.013
D	1.270	0.130	0.050	0.005
E	1.020	0.130	0.040	0.005
F	1.700	0.130	0.067	0.005
G	0.130	0.025	0.005	0.001
Н	8.130	0.250	0.320	0.010
I	45°	5°	45°	5°
J	5.080	0.250	0.200	0.010
K	2.54 DIA	0.130	.100 DIA	0.005
L	1.270	0.130	0.050	0.005
M	9.530	0.130	0.375	0.005

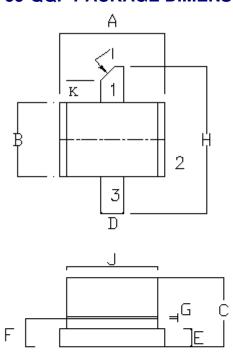
PIN 1: DRAIN PIN 2: SOURCE PIN 3: GATE





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### 55-QQP PACKAGE DIMENSION



Dim	Millimeter	Tol	Inches	Tol
Α	5.84	.25	.230	.010
В	4.06	.25	.160	.010
С	3.17	.05	.125	.002
D	1.27	.13	.050	.005
E	1.02	.13	.040	.005
F	1.57	.13	.062	.005
G	.130	.02	.005	.001
Н	8.12	.25	.320	.010
I	45°	5°	45°	5°
J	5.08	.25	.200	.010
K	1.40	.13	.055	.005

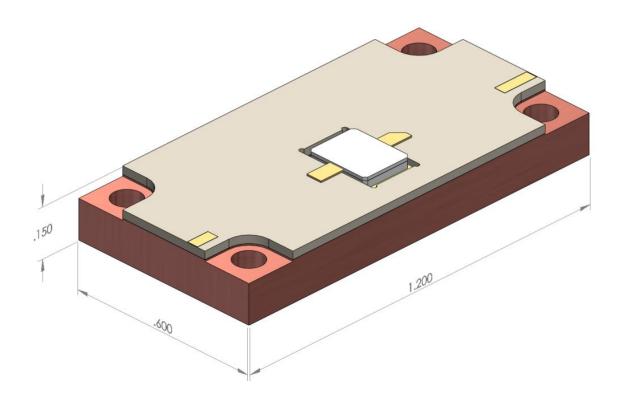
PIN 1: DRAIN PIN 2: SOURCE PIN 3: GATE





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### 55-78029 CASE OUTLINE OVERALL PALLET DIMENSION



Dimensions: Length=1.200" x Width=0.600" x Height=0.150"



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#### Revision History

Revision Level / Date	Para. Affected	Description
Rev 1 / 12 Dec 2014	Initial	First release